



# A study on five different channel shapes using a novel scheme for meshing and a structure of a multi-nozzle microchannel heat sink



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## ABSTRACT

In this study, a copper plate measuring 9.8 mm × 9.8 mm × 0.5 mm was used as a fixed substrate for designs with single-layer-and-parallel or multi-nozzle microchannel heat sinks. Water was applied as the coolant. Channel lengths from 0.2 to 5.6 mm and five different channel shapes, including a circle, square, trapezium, two concave surfaces, and two convex surfaces, were numerically investigated in detail at a constant hydraulic diameter of 200 μm with a Reynolds number in the range of 700–2200. A novel scheme for meshing was proposed. A structure for a multi-nozzle microchannel heat sink was presented. For all cases in this study, it was found that the best thermal performance was achieved with a circular channel shape which could dissipate a heat flux up to 1500 W/cm<sup>2</sup>, and the maximum temperature was kept at less than 75 °C at a Reynolds number of 2200. Furthermore, novel equations were proposed to predict the temperature differences between inlet and outlet coolant temperatures depending on the channel length and Reynolds number, as well as to predict the maximum temperatures on the bottom walls of the circular channel shape depending on the Reynolds number and heat flux.

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## 1. Introduction

Requirements for the heat dissipation capacity and maximum working temperature for each applied field were different. For example, the maximum power flux for chips, reported by Phillips [1], was around 100 W/cm<sup>2</sup>, and the maximum working temperature for this field was about 100 °C. The VLSI industry requires a heat flux up to 10<sup>3</sup> W/cm<sup>2</sup> and a maximum working temperature of 125 °C, as reported by Mudawar [2], and Lee and Mudawar [3], respectively. These demands have grown every single day and have gradually exceeded the heat dissipation capabilities of air-cooling heat sinks; therefore, fluid-cooling heat sinks have been employed. In 1981, Tuckerman and Pease [4] first proposed a microchannel heat sink (MCHS) for VLSI with a heat flux of 790 W/cm<sup>2</sup>. Since then, the MCHS has been investigated in many aspects. Single-layer and parallel microchannel heat sinks (SL-P-MCHS) have been found in a great number of investigations in the MCHS field. This may divide ideas in published literature for enhancing thermal performance of a microchannel heat sink into two main solution groups as follows: (1) using substrate materials and coolants with higher thermal conductivity and (2) creating optimal structures for

heat sinks in general and for channels, manifolds or inlet–outlets in particular. The influences of substrates' thicknesses and the type of materials on heat transfer in MCHS were investigated by Kosar [5]. Kosar found that substrate-thermal conductivity affected the change in thermal resistance much more than the effect of the substrate's thickness. For increasing thermal conductivities of the coolant, Choi and Eastman [6] first used the term, nanofluids, in 1995. Two year later, Eastman et al. [7] reported that a nanofluid, including water and 5% CuO nano-particles, could improve thermal conductivity by approximately 60% compared to water alone. For the geometric structure of MCHS, Zhang et al. [8,9] and Yu et al. [10] reported investigations on fractal-like MCHS. They found that fractal tree-like MCHS has a much higher heat transfer coefficient than that of straight microchannels, but it requires a much higher pumping power. Leng et al. [11] studied porous fin MCHS, and their research revealed that the pressure drop on porous fin MCHS could decrease remarkably compared to solid fins. Circular and square channel shapes were investigated by Normah et al. [12]. They concluded that at the same hydraulic diameter and pumping power, the thermal resistance of a circular MCHS was lower than that of a square MCHS. Wong et al. [13] studied the triangular fin shape, and Chu et al. [14] studied the triangular channel shape. They reported that the heat transfer rate increased with the increase in the rib width or height, but it decreased with the increase in the rib length [13]. A high temperature gradient was found in the

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